

L Number	Hits	Search Text	DB	Time stamp
2	1	("666T098").PN.	USPAT	2004/07/28 16:54
3	1		USPAT	2004/07/28 16:52
4	1		USPAT	2004/07/28 16:52
5	1		USPAT	2004/07/28 16:53
6	1		USPAT	2004/07/28 16:53
7	0	(microjoint adj interconnect) and carrier and substrate and component and adhesion and diffusion and barrier and noble and metal and fusible and solder and ball and pad	USPAT	2004/07/28 16:57
8	0	(microjoint adj interconnect) and carrier and substrate and component and noble and metal and fusible and solder and ball and pad	USPAT	2004/07/28 16:57
9	0	(microjoint adj interconnect) and carrier and substrate and component and noble and metal and fusible	USPAT	2004/07/28 16:58
10	1	(microjoint adj receptacles) and carrier and substrate and component and noble and metal and fusible	USPAT	2004/07/28 16:59
11	0	(microjoint adj receptacles) and carrier and substrate and component and noble and metal and fusible and (microjoint adj interconnect)	USPAT	2004/07/28 17:00
12	1	(microjoint adj receptacles) and carrier and substrate and component and noble and metal and fusible and (fusible adj solder adj joint adj ball)	USPAT	2004/07/28 17:10
13	2259	257/678	USPAT	2004/07/28 17:11
14	589	257/770	USPAT	2004/07/28 17:11
15	415	257/771	USPAT	2004/07/28 17:11
16	622	257/768	USPAT	2004/07/28 17:11
17	356	257/769	USPAT	2004/07/28 17:11
18	2715	257/737	USPAT	2004/07/28 17:11
19	2376	257/738	USPAT	2004/07/28 17:11
20	3451	257/778	USPAT	2004/07/28 17:12
21	1309	257/779	USPAT	2004/07/28 17:12
22	2047	257/777	USPAT	2004/07/28 17:12
-	1	10/052620	USPAT	2004/07/28 16:51

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